

SBVS003B - JANUARY 1993 - REVISED JANUARY 2005

+5V Precision VOLTAGE REFERENCE

FEATURES

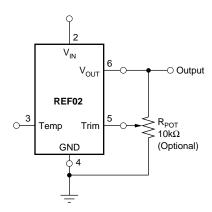
- OUTPUT VOLTAGE: +5V ±0.2% max
- EXCELLENT TEMPERATURE STABILITY: 10ppm/°C max (-40°C to +85°C)
- LOW NOISE: 10µV_{PP} max (0.1Hz to 10Hz)
- EXCELLENT LINE REGULATION: 0.01%/V max
- EXCELLENT LOAD REGULATION: 0.008%/mA max
- LOW SUPPLY CURRENT: 1.4mA max
- SHORT-CIRCUIT PROTECTED
- WIDE SUPPLY RANGE: 8V to 40V
- INDUSTRIAL TEMPERATURE RANGE: -40°C to +85°C
- PACKAGE OPTIONS: DIP-8, SO-8

APPLICATIONS

- PRECISION REGULATORS
- CONSTANT CURRENT SOURCE/SINK
- DIGITAL VOLTMETERS
- V/F CONVERTERS
- A/D AND D/A CONVERTERS
- PRECISION CALIBRATION STANDARD
- TEST EQUIPMENT

DESCRIPTION

The REF02 is a precision 5V voltage reference. The drift is laser trimmed to 10ppm/°C max over the extended industrial and military temperature range. The REF02 provides a stable 5V output that can be externally adjusted over a ±6% range with minimal effect on temperature stability. The REF02 operates from a single supply with an input range of 8V to 40V with a very low current drain of 1mA, and excellent temperature stability due to an improved design. Excellent line and load regulation, low noise, low power, and low cost make the REF02 the best choice whenever a 5V voltage reference is required. Available package options are DIP-8 and SO-8. The REF02 is an ideal choice for portable instrumentation, temperature transducers, Analog-to-Digital (A/D) and Digital-to-Analog (D/A) converters, and digital voltmeters.



+5V Reference with Trimmed Output



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.



SPECIFICATIONS

ELECTRICAL

At $T_A = +25$ °C and $V_{IN} = +15$ V power supply, unless otherwise noted.

| | | | REF02A | | | REF02B | | |
|---|--|-------|----------------|----------------|-------|-----------|----------------|------------------|
| PARAMETER | CONDITIONS | MIN | TYP | MAX | MIN | TYP | MAX | UNITS |
| OUTPUT VOLTAGE Change with Temperature ^(1, 2) (ΔV _{OT}) -40°C to +85°C | I _{LOAD} = 0mA | 4.985 | 5.0 0.05 | 5.015 0.19 | 4.990 | * 0.05 | 5.010 0.13 | V % |
| OUTPUT VOLTAGE DRIFT ⁽³⁾ -40°C to +85°C (TCV _O) | | | 4 | 15 | | 4 | 10 | ±ppm/°C |
| LONG-TERM STABILITY First 1000h Second 1000h | 2000h Test | | 100 50 | | | 100 50 | | ±ppm ±ppm |
| OUTPUT ADJUSTMENT RANGE | $R_{POT} = 10k\Omega^{(6)}$ | ±3 | ±6 | | * | * | | % |
| CHANGE IN V _O TEMP COEFFICIENT WITH OUTPUT ADJUSTMENT (-55°C to +125°C) | R _{POT} = 10kΩ | | 0.7 | | | * | | ppm/% |
| OUTPUT VOLTAGE NOISE | 0.1Hz to 10Hz ⁽⁵⁾ | | 4 | 10 | | * | * | μV _{PP} |
| LINE REGULATION ⁽⁴⁾ -40°C to +85°C | $V_{IN} = 8V \text{ to } 33V$ $V_{IN} = 8.5V \text{ to } 33V$ | | 0.006 0.008 | 0.010 0.012 | | * | * | %/V |
| LOAD REGULATION ⁽⁴⁾ -40°C to +85°C | $I_L = 0$ mA to +10mA $I_L = 0$ mA to +10mA | | 0.005 0.007 | 0.010 0.012 | | * | 0.008 0.010 | %/mA |
| TURN-ON SETTLING TIME | To ±0.1% of Final Value | | 5 | | | * | | μs |
| QUIESCENT CURRENT | No Load | | 1.0 | 1.4 | | * | * | mA |
| LOAD CURRENT (SOURCE) | | 10 | 21 | | * | * | | mA |
| LOAD CURRENT (SINK) | | -0.3 | -0.5 | | * | * | | mA |
| SHORT-CIRCUIT CURRENT | V _{OUT} = 0 | | 30 | | | * | | mA |
| POWER DISSIPATION | No Load | | 15 | 21 | | * | * | mW |
| TEMPERATURE VOLTAGE OUTPUT ⁽⁷⁾ | | | 630 | | | * | | mV |
| TEMPERATURE COEFFICIENT of Temperature Pin Voltage -55°C to +125°C | | | 2.1 | | | | | mV/°C |
| TEMPERATURE RANGE Specification REF02A, B, C | | -40 | | +85 | * | | * | °C |

NOTES: (1) ΔV_{OT} is defined as the absolute difference between the maximum output and the minimum output voltage over the specified temperature range expressed as a percentage of 5V: $\Delta V_{O} = \left| \frac{V_{MAX} - V_{MIN}}{5V} \right| \times 100$

- (2) ΔV_{OT} specification applies trimmed to +5.000V or untrimmed.
- (3) TCV $_{\rm O}$ is defined as $\Delta {\rm V}_{\rm OT}$ divided by the temperature range.
- (4) Line and load regulation specifications include the effect of self heating.
- (5) Sample tested.
- (6) $10k\Omega$ potentiometer connected between V_{OUT} and ground with wiper connected to Trim pin. See figure on page 1.
- (7) Pin 3 is insensitive to capacitive loading. The temperature voltage will be modified by 7mV for each μ A of loading.



ABSOLUTE MAXIMUM RATINGS

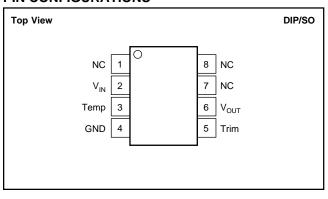
| Input Voltage | +40V |
|--|---------------|
| Operating Temperature | |
| P, U | 40°C to +85°C |
| Storage Temperature Range | |
| P, U | 65°C to +125° |
| Output Short Circuit Duration (to Ground or VIN) | Indefinite |
| Junction Temperature | 65°C to +150° |
| θ _{IΔ} P | 120°C/W |
| U | 80°C/W |
| Lead Temperature (soldering, 60s) | +300°C |
| I and the second | |

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PIN CONFIGURATIONS



PACKAGE/ORDERING INFORMATION(1)

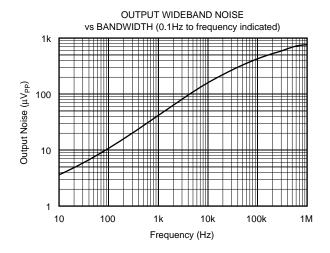
| PRODUCT | V _{ou⊤} at 25°C | MAX DRIFT (ppm/°C) | PACKAGE | PACKAGE DRAWING DESIGNATOR | SPECIFICATION TEMPERATURE RANGE |
|---------|--------------------------|-----------------------|---------|----------------------------------|---------------------------------------|
| REF02AU | 5V±15mV | ±15 | SO-8 | D | -40°C to +85°C |
| REF02BU | 5V±10mV | ±10 | SO-8 | D | -40°C to +85°C |
| REF02AP | 5V±15mV | ±15 | DIP-8 | Р | -40°C to +85°C |
| REF02BP | 5V±10mV | ±10 | DIP-8 | Р | -40°C to +85°C |

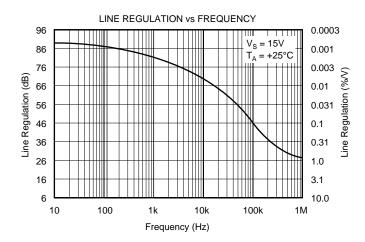
NOTE: (1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet, or see the TI website at www.ti.com.

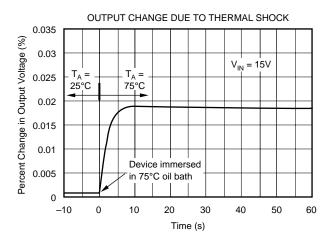


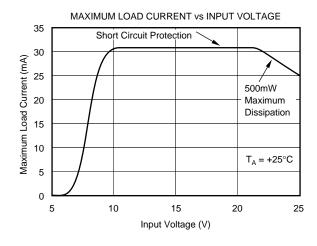
TYPICAL PERFORMANCE CURVES

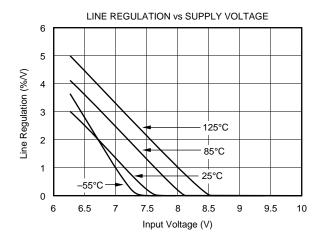
AT $T_A = +25^{\circ}C$, unless otherwise noted.

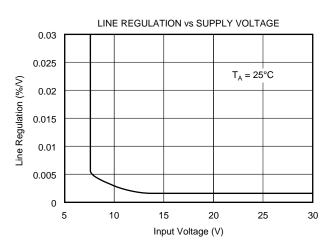








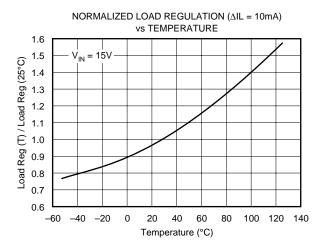


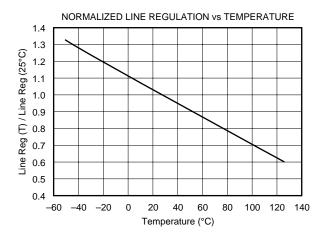


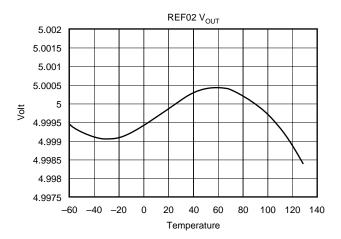


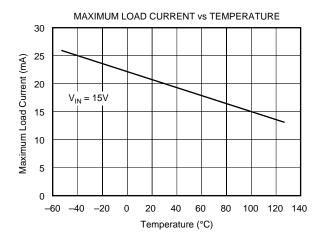
TYPICAL PERFORMANCE CURVES (Cont.)

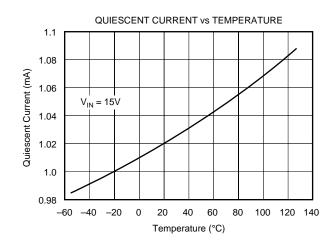
At $T_A = +25$ °C, unless otherwise noted.

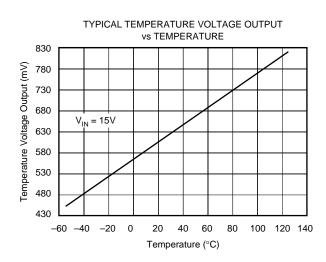








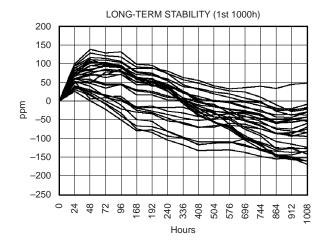


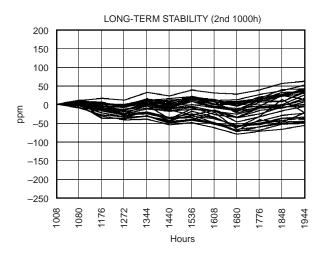


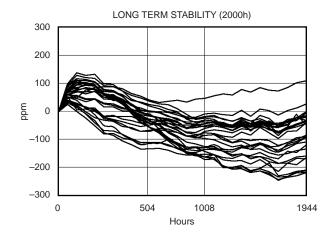


TYPICAL PERFORMANCE CURVES (Cont.)

At $T_A = +25$ °C, unless otherwise noted.







OUTPUT ADJUSTMENT

The REF02 trim terminal can be used to adjust the voltage over a $5V \pm 150 mV$ range. This feature allows the system designer to trim system errors by setting the reference to a voltage other than 5V, including $5.12V^{(1)}$ for binary applications (see circuit on page 1).

Adjustment of the output does not significantly affect the temperature performance of the device. The temperature coefficient change is approximately 0.7ppm/°C for 100mV of output adjustment.

NOTE: (1) 20mV LSB for 8-bit applications.

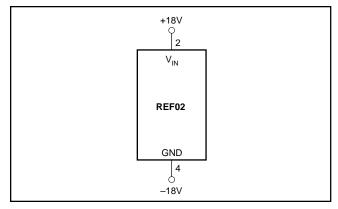


FIGURE 1. Burn-In Circuit.

REFERENCE STACKING PROVIDES OUTSTANDING LINE REGULATION

By stacking two REF01s and one REF02, a systems designer can achieve 5V, 15V, and 25V outputs. One very important advantage of this circuit is the near-perfect line regulation at 5V and 15V outputs. This circuit can accept a 27V to 55V change to the input with less than the noise voltage as a change to the output voltage. $R_{\rm B}$, a load bypass resistor, supplies current $I_{\rm SY}$ for the 15V regulator.

Any number of REF01s and REF02s can be stacked in this configuration. For example, if ten devices are stacked in this configuration, ten 5V or five 10V outputs are achieved. The line voltage may range from 100V to 130V. Care should be exercised to insure that the total load currents do not exceed the maximum usable current, which is typically 21mA.

TYPICAL APPLICATIONS

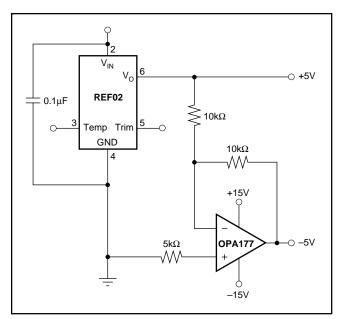


FIGURE 2. ±5V Precision Reference.



www.ti.com 13-Jan-2024

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|--------------|-------------------------------|---------------------|--------------|-------------------------|---------|
| REF02AU | ACTIVE | SOIC | D | 8 | 75 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | REF 02AU | Samples |
| REF02AU/2K5 | ACTIVE | SOIC | D | 8 | 2500 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | REF 02AU | Samples |
| REF02BU | ACTIVE | SOIC | D | 8 | 75 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | REF 02BU | Samples |
| REF02BU/2K5 | ACTIVE | SOIC | D | 8 | 2500 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | REF 02BU | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and



PACKAGE OPTION ADDENDUM

www.ti.com 13-Jan-2024

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 1-Jan-2024

TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

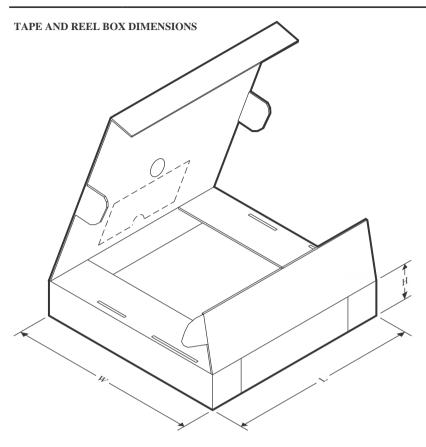
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|------|--------------------|---|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| REF02AU/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| REF02BU/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |

www.ti.com 1-Jan-2024



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|--|
| REF02AU/2K5 | SOIC | D | 8 | 2500 | 356.0 | 356.0 | 35.0 | |
| REF02BU/2K5 | SOIC | D | 8 | 2500 | 356.0 | 356.0 | 35.0 | |

PACKAGE MATERIALS INFORMATION

www.ti.com 1-Jan-2024

TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|---------|--------------|--------------|------|-----|--------|--------|--------|--------|
| REF02AU | D | SOIC | 8 | 75 | 506.6 | 8 | 3940 | 4.32 |
| REF02BU | D | SOIC | 8 | 75 | 506.6 | 8 | 3940 | 4.32 |



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2024, Texas Instruments Incorporated